



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(ON) Max	I _D Max T _A = +25°C
20V	0.99Ω @ V _{GS} = 4.5V	0.45A
	1.2Ω @ V _G S = 2.5V	0.40A
	1.8Ω @ V _{GS} = 1.8V	0.34A
	2.4Ω @ V _{GS} = 1.5V	0.30A

Description and Applications

This MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$ yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- General purpose interfacing switches
- Power-management functions
- Analog switches

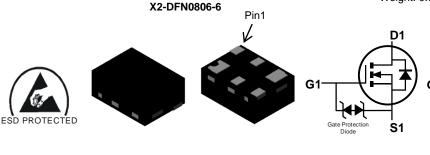
Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V maximum
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface-Mount Package 0.8mm x 0.6mm
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

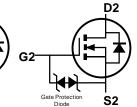
Mechanical Data

- Package: X2-DFN0806-6
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 3
- Weight: 0.001 grams (Approximate)

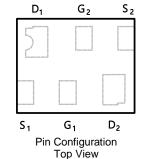




Bottom View



Device Symbol



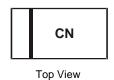
Ordering Information (Note 4)

Orderable Part Number	Pankaga	Packing		
	Package	Qty.	Carrier	
DMN2991UDA-7B	X2-DFN0806-6	10.000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



CN = Product Type Marking Code



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			Vgss	±8	V
Continuous Prain Current (Note 5)	Steady	T _A = +25°C	- I _D	0.45	- A
Continuous Drain Current (Note 5)	State	T _A = +70°C		0.36	
Pulsed Drain Current (Note 6)			I _{DM}	1.2	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

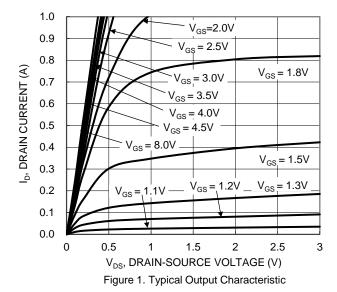
Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P _D	0.31	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	404	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

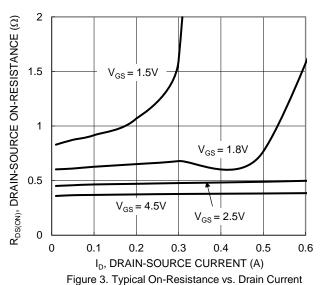
Electrical Characteristics ($@T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage		BV _{DSS}	20	_	_	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current @Tc =	+25°C	IDSS	_	_	1	μΑ	V _{DS} = 16V, V _{GS} = 0V	
Gate-Source Leakage		Igss	_	—	±10	μΑ	$V_{GS} = \pm 5V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage		Vgs(TH)	0.4	0.78	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
				0.47	0.99		$V_{GS} = 4.5V, I_D = 100mA$	
Static Drain-Source On-Resistance		RDS(ON)		0.63	1.2	Ω	$V_{GS} = 2.5V, I_{D} = 50mA$	
Static Dialif-Source Off-Nesistance		NDS(ON)		0.84	1.8	32	$V_{GS} = 1.8V, I_{D} = 20mA$	
				1.1	2.4		$V_{GS} = 1.5V, I_D = 10mA$	
Diode Forward Voltage		VsD	_	0.6	1.0	V	$V_{GS} = 0V$, $I_{S} = 10mA$	
DYNAMIC CHARACTERISTICS (Note 8)			1			•		
Input Capacitance		Ciss	_	21.5	_	pF	101/1/	
Output Capacitance		Coss	_	4.9		pF	V _{DS} = 16V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance		Crss		3.7		рF	T = T.OWHZ	
Gate Resistance		R_g		0.94	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge		Q_g	_	0.35		nC	1, 151/1/ 101/	
Gate-Source Charge		Q_gs		0.07		nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 250 \text{mA}$	
Gate-Drain Charge		Q_gd	_	0.08		nC	10 = 23011A	
Turn-On Delay Time		td(on)		5.6		ns	$\begin{aligned} & V_{DD} = 10 V, V_{GS} = 4.5 V, \\ & R_L = 47 \Omega, R_g = 10 \Omega, \\ & I_D = 200 mA \end{aligned}$	
Turn-On Rise Time		tr	_	4.9		ns		
Turn-Off Delay Time		tD(OFF)	_	60.6	_	ns		
Turn-Off Fall Time		tF	_	27.6	_	ns		
Reverse Recovery Time		t _{RR}		12.3	_	ns	$I_F = 1.0A$, $di/dt = 100A/\mu s$	
Reverse Recovery Charge		Q_{RR}	_	1.1		nC	I _F = 1.0A, di/dt = 100A/μs	

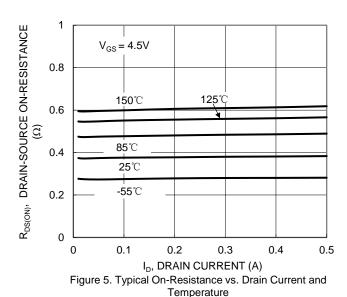
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%. 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.

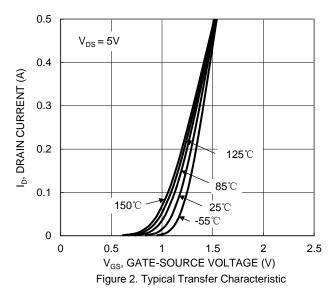






and Gate Voltage





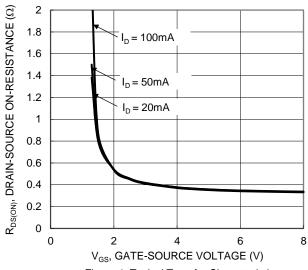


Figure 4. Typical Transfer Characteristic

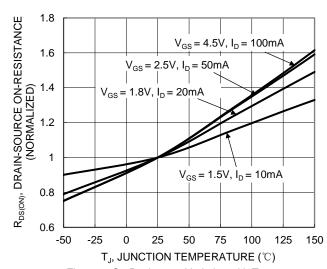


Figure 6. On-Resistance Variation with Temperature



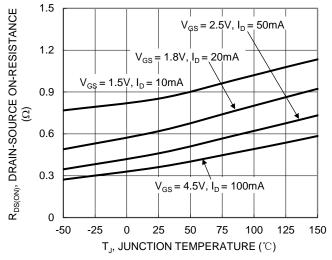
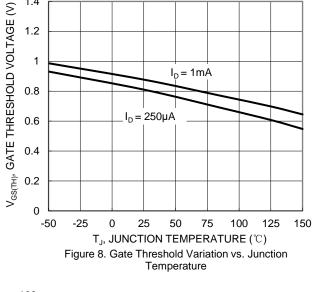


Figure 7. On-Resistance Variation with Temperature



1.4

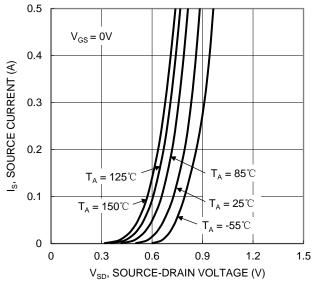


Figure 9. Diode Forward Voltage vs. Current



Qg (nC) Figure 11. Gate Charge

0.3

 $V_{DS} = 10V, I_{D} = 250mA$

0.4

0.5

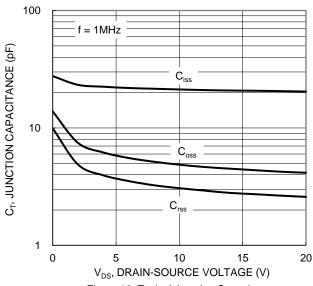


Figure 10. Typical Junction Capacitance

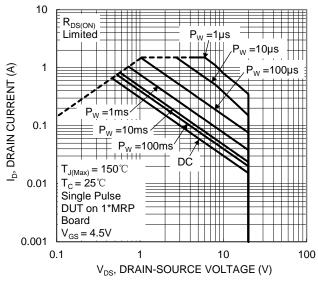


Figure 12. SOA, Safe Operation Area

8

7

6

5

3

2

1

0

0

0.1

0.2

 $V_{GS}(V)$



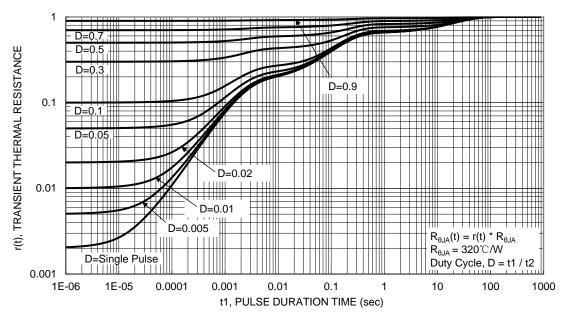


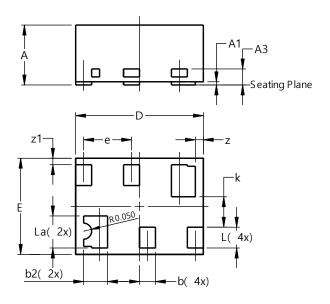
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN0806-6

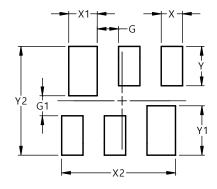


X2-DFN0806-6					
Dim	Min	Max	Тур		
Α		0.40	0.36		
A1	0.00	0.03	0.02		
A3			0.10		
b	0.07	0.15	0.10		
b2	0.10	0.20	0.15		
D	0.75	0.85	0.80		
Е	0.55	0.65	0.60		
е			0.30		
k			0.19		
٦	0.10	0.18	0.13		
La	0.17	0.25	0.20		
z			0.05		
z1			0.04		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN0806-6



Dimensions	Value (in mm)
G	0.150
G1	0.140
Х	0.150
X1	0.200
X2	0.800
Υ	0.275
Y1	0.345
Y2	0.760



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